

# 105 Reliability & Qualification Data

This is the reliability & qualification data for the 105 memory controller & bridge chip. At this time we do not have FIT and MTBF graphs for this device.

Stress	Results
Lifetest EFR (4.25V,125°C)	1/326 =0.3% @ 168 hours (data from 6 lots)
Lifetest (4.25V,125°C) Other devices, same process	1/1868 @ 1008 hours, 1/2926 @ 504 hours, 11/6699 @ 168 hours
Bake (175°C) Other devices, same process	1/1690 @ 1000 hours
ESD:	
Human Body Model	0/15: Pass 2000V
Charged Device Model	0/15: Pass 500V
Machine Model	0/15: Pass 200V
Latchup	0/15: Pass +/-200mA, No Latchup Observed
<b>304 LEAD (21 x 25 mm) CBGA PACKAGE</b>	
Stress	Results
Moisture Characterization	0/15, Level 1 Package - No Drypack Required
Temp Cycle 0°C/100°C (21x21mm 603/604 data) (21x25mm 105 data)	0/335 @ 100 cyc, 0/215 @ 500 cyc 1/286 @ 1000 cyc
Temp Cycle -55°C/125°C (21x21mm 603P data) (21x25mm 105 data)	0/96 @ 500 cyc, 0/66 @ 1000 cyc 0/145 @ 1000 cyc
Autoclave (21x21mm 603P data) (21x25mm 105 data)	0/139 @ 144 hrs 0/133 @ 48 hrs
Bake 150°C (21x25mm 105 data)	0/231 @ 1008 hrs
THB 85°C/85% RH (21x25 mm 105 data)	0/224 @ 1008 hrs